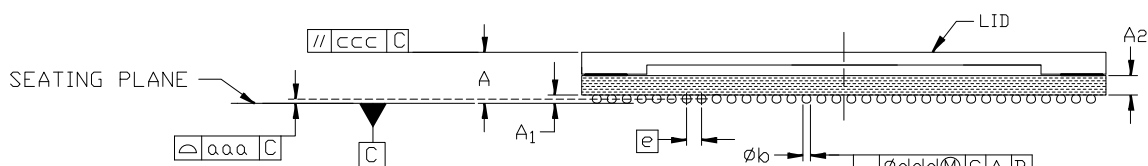
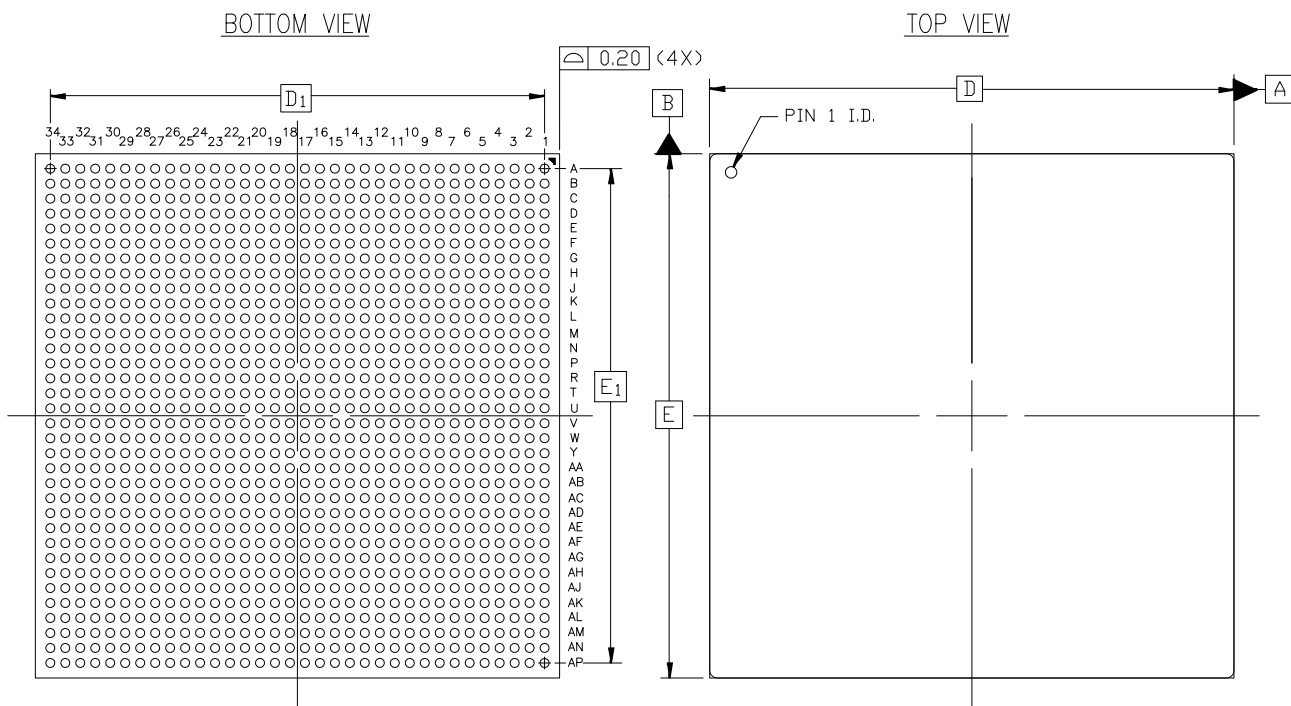












1156 Ball Flip-Chip BGA (FF1155/FFG1155) Package



FF1155 - Sn/Pb SOLDER BALLS
FFG1155 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.70		3.50	2
A ₁	0.40	0.50	0.60	
A ₂	0.90		1.50	
D/E	35.00 BASIC			
D ₁ /E ₁	33.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa			0.20	
ccc			0.35	
ddd			0.25	
eee			0.10	
M	34			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAR-1
4. ACTUAL SOLDER BALL COUNT = 1156

UG393_01_091009

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/23/09	1.0	Initial Xilinx release.

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